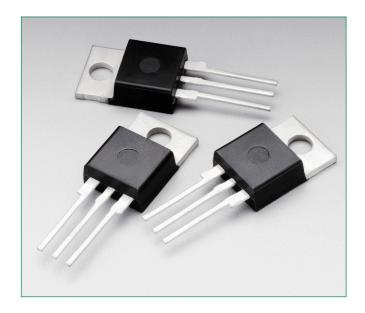


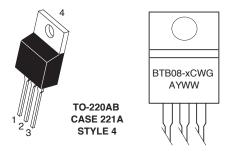
## Surface Mount - 600 - 800V > BTB08-600CW3G, BTB08-800CW3G

# BTB08-600CW3G, BTB08-800CW3G





# Pin Out



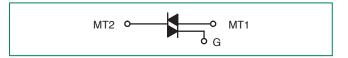
#### **Description**

Designed for high performance full-wave ac control applications where high noise immunity and high commutating di/dt are required.

#### **Features**

- Blocking Voltage to 800 V
- On-State Current Rating of 8 A RMS at 80°C
- Uniform Gate Trigger Currents in Three Quadrants
- High Immunity to dV/dt 1500 V/s minimum at 125°C
- Minimizes Snubber Networks for Protection
- Industry Standard TO-220AB Package
- High Commutating dl/dt 3.0 A/ms minimum at 125°C
- These Devices are Pb-Free

#### **Functional Diagram**



#### Additional Information







Samples

## **Maximum Ratings** † $(T_J = 25^{\circ}C \text{ unless otherwise noted})$

Rating	Part Number	Symbol	Value	Unit	
Peak Repetitive Off-State Voltage (Note 1)	BTB08-600CW3G	$V_{DRM,}$	600	V	
$(T_J = -40 \text{ to } 125^{\circ}\text{C}, \text{ Sine Wave, } 50 \text{ to } 60 \text{ Hz, Gate Open})$	BTB08-800CW3G	$V_{RRM}$	800		
On-State RMS Current (Full Cycle Sine Wave, 60 Hz, TC = 80°C)			8.0	А	
Peak Non–Repetitive Surge Current (One Full Cycle Sine Wave, 60 Hz,T <sub>c</sub> = 25°C)		I <sub>TSM</sub>	90	А	
Circuit Fusing Considerations (t = 10 ms)			36	A <sup>2</sup> sec	
Non-Repetitive Surge Peak Off-State Voltage (T <sub>J</sub> = 25°C, t = 10ms)			V <sub>DRM</sub> /V <sub>RRM</sub> +100	V	
Peak Gate Current ( $T_J = 125$ °C, t = 20ms)			4.0	А	
Peak Gate Power (Pulse Width ≤ 1.0 μs, TC = 80°C)			20	W	
Average Gate Power ( $T_J = 125^{\circ}C$ )			1.0	W	
Operating Junction Temperature Range			-40 to +125	°C	
Storage Temperature Range			-40 to +150	°C	

<sup>†</sup> Indicates JEDEC Registered Data

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### **Maximum Ratings** † (T<sub>J</sub> = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (AC)	R <sub>eJC</sub>	2.5	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>eJA</sub>	60	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	T <sub>L</sub>	260	°C

<sup>†</sup> Indicates JEDEC Registered Data

V<sub>DRM</sub> and V<sub>RRM</sub> for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; however, positive gate voltage shall
not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the
voltage ratings of the devices are exceeded.



# $Surface\ Mount-600-800V\ >\ BTB08-600CW3G,\ BTB08-800CW3G$

## **Electrical Characteristics** - **OFF** (T<sub>c</sub> = 25°C unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
Peak Repetitive Blocking Current $(V_D = V_{DRM} = V_{RRM}; Gate Open)$	T <sub>J</sub> = 25°C	l <sub>DRM</sub> ,	-	-	0.005	Λ
	T <sub>J</sub> = 125°C	I <sub>RRM</sub>	-	-	1.0	ł mA

#### **Electrical Characteristics - ON**

Characteristic		Symbol	Min	Тур	Max	Unit
Peak On-State Voltage (Note 2) (I <sub>TM</sub> = ±11 A Peak)		V <sub>TM</sub>	_	_	1.55	V
	MT2(+), G(+)		2.5	-	35	
Gate Trigger Current (Continuous dc) ( $V_D = 12 \text{ V}, R_L = 30 \Omega$ )	MT2(+), G(-)	I <sub>GT</sub>	2.5	-	35	mA
	MT2(-), G(-)		2.5	_	35	
Holding Current ( $V_D = 12 \text{ V}$ , Gate Open, Initiating Current = $\pm 100 \text{ mA}$	)	I <sub>H</sub>	-	_	45	mA
	MT2(+), G(+)		-	_	50	
Latching Current $(V_D = 24 \text{ V}, I_G = 42 \text{ mA})$	MT2(+), G(-)	I <sub>L</sub>	-	-	80	mA
	MT2(-), G(-)		-	_	50	
	MT2(+), G(+)		0.5	-	1.7	
Gate Trigger Voltage $(V_D = 12 \text{ V}, R_L = 30 \Omega)$	MT2(+), G(-)	V <sub>GT</sub>	0.5	_	1.1	V
	MT2(-), G(-)		0.5	_	1.1	
	MT2(+), G(+)		0.2	-	-	
Gate Non-Trigger Voltage (T <sub>J</sub> = 125°C)	MT2(+), G(-)	$V_{GD}$	0.2	-	-	V
	MT2(-), G(-)		0.2	_	-	

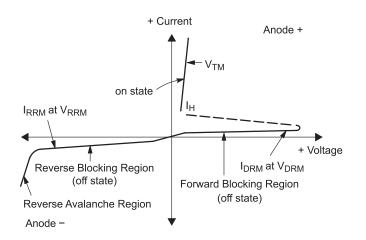
<sup>2.</sup> Indicates Pulse Test: Pulse Width  $\leq$  2.0 ms, Duty Cycle  $\leq$  2%.

#### **Dynamic Characteristics**

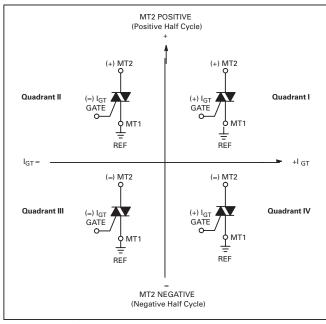
Characteristic	Symbol	Min	Тур	Max	Unit
Rate of Change of Commutating Current, See Figure 10. (Gate Open, TJ = 125°C, No Snubber)	(dl/dt) <sub>c</sub>	3.0	_	_	A/ms
Critical Rate of Rise of On-State Current (TJ = $125^{\circ}$ C, f = $120$ Hz, IG = $2 \times IGT$ , tr $\leq 100$ ns)	dl/dt	-	-	50	A/µs
Critical Rate-of-Rise of Off-State Voltage $(V_D = 0.66 \times V_{DRM}, Exponential Waveform, Gate Open, T_J = 125°C)$	dv/dt(c)	1500	_	_	V/µs

#### **Voltage Current Characteristic of SCR**

Symbol	Parameter
V <sub>DRM</sub>	Peak Repetitive Forward Off State Voltage
I <sub>DRM</sub>	Peak Forward Blocking Current
V <sub>RRM</sub>	Peak Repetitive Reverse Off State Voltage
I <sub>RRM</sub>	Peak Reverse Blocking Current
V <sub>TM</sub>	Maximum On State Voltage
I <sub>H</sub>	Holding Current



#### **Quadrant Definitions for a Triac**



All polarities are referenced to MT1.
With in-phase signals (using standard AC lines) quadrants I and III are used



#### **Figure 1. RMS Current Derating**

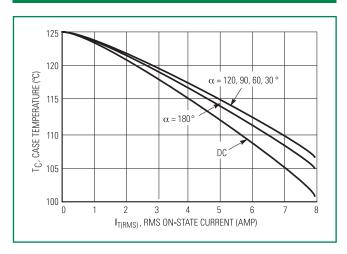


Figure 3. On-State Characteristics

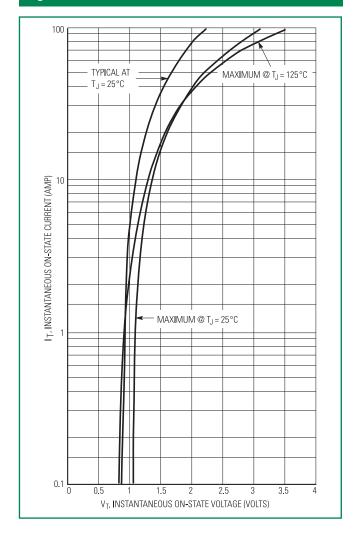


Figure 2. On-State Power Dissipation

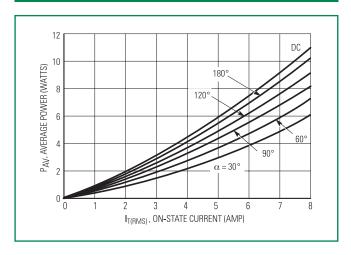


Figure 4. Thermal Response

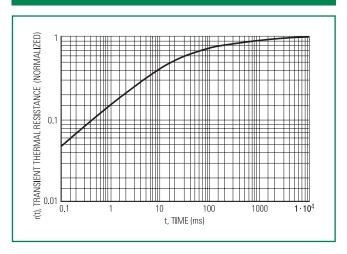
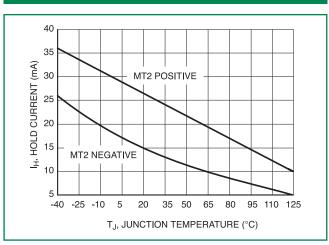


Figure 5. Typical Hold Current Variation





#### **Typical Characteristics**

#### Figure 6. Typical Gate Trigger Current Variation

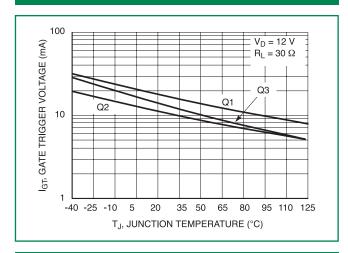


Figure 7. Typical Gate Trigger Current Variation

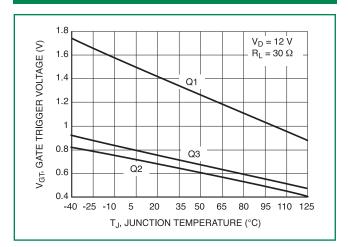


Figure 8. Critial Rate of Rise of Off-State Voltage (Exponential Waveform)

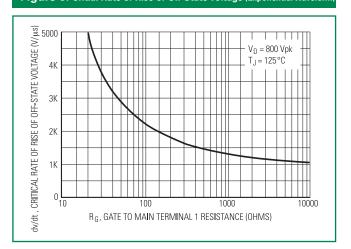
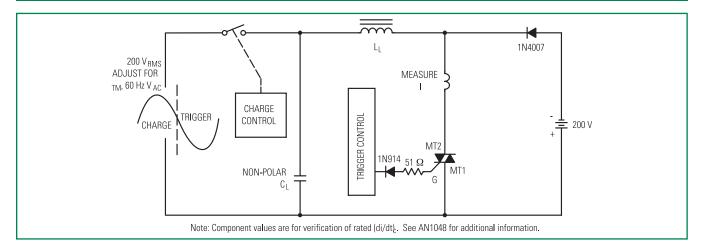
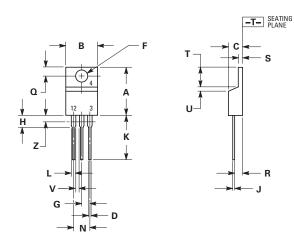


Figure 9. Simplified Test Circuit to Measure the Critical Rate of Rise of Commutating Current  $\left(\frac{di}{dt}\right)_c$ 



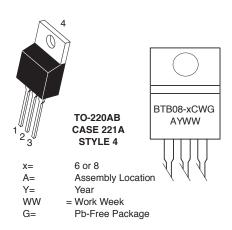
#### **Dimensions**



	Inches		Millin	neters
Dim	Min	Max	Min	Max
А	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.014	0.022	0.36	0.55
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045		1.15	
Z		0.080		2.04

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

#### **Part Marking System**



Pin Assignment	
1	Main Terminal 1
2	Main Terminal 2
3	Gate
4	Main Terminal 2

# Ordering Information Device Package Shipping BTB08-600CW3G TO-220AB 50 Units / Retail

(Pb-Free)

BTB08-800CW3G

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